In the Specification

Please amend the paragraph beginning on page 3, line 20 as follows:

A1

Shaft 12 may be comprised of materials including, but not limited to, metals, stainless steel, nickel alloys, nickel-titanium alloys, thermoplastics, high performance engineering resins, fluorinated ethylene propylene (FEP), polymer, polyethylene (PE), polypropylene (PP), polyvinylchloride (PVC), polyurethane, ~~polytetrafluoroethylene~~ polytetraflouroethylene (PTFE), polyether block amide (PEBA), polyether-ether ketone (PEEK), polyimide, polyamide, polyphenylene sulfide (PPS), polyphenylene oxide (PPO), ~~polysufone~~ polysulfone, nylon, ~~perfluoro~~perflouro(propyl vinyl ether) (PFA), and combinations thereof.

Please amend the paragraph beginning on page 6, line 1 as follows:

A2

A heat source 26 may be disposed proximate solder ball 22. It should be understood that multiple locations of heat source 26 relative to solder ball22 may be used without departing from the scope of the invention, for example behind or under solder ball 22. Heat source 26 may be capable of increasing the temperature of solder ball 22 such that at least a portion thereof melts. For example, heat source 26 may have a temperature of about 460°C. Alternatively, heat source 26 may have a temperature up to about, for example, 600°C or greater. The heat cycle time that solder ball 22 is exposed to heat source 26 may also ~~very~~ vary. For example, the cycle time of exposure may be up to about 5 seconds or more.

Please amend the paragraph beginning on page 7, line 4 as follows:

Guidewire 10 may further comprise a heat shrink tube 28 coupled to shaft 12. Heat shrink tube 28 may be used to prevent proximal migration of flux 24 similar to what is described above and may provide a barrier ~~to~~ for the prevention of proximal migration of flux 24. Heat shrink tube 28 may be comprised of ~~polytetrafluoroethylene~~ polytetraflouroethylene and coupled to shaft 12. Heat shrink 28 may remain coupled to shaft 12 after manufacturing of guidewire 10 or may be removed after manufacturing.